

## Quad Darlington switch

### Features

- Four non-inverting inputs with enable
- Output voltage up to 50 V
- Output current up to 1.8 A
- Very low saturation voltage
- TTL compatible inputs
- Integral fast recirculation diodes

### Applications

The L6221 monolithic quad Darlington switch is designed for high current, high voltage switching applications.

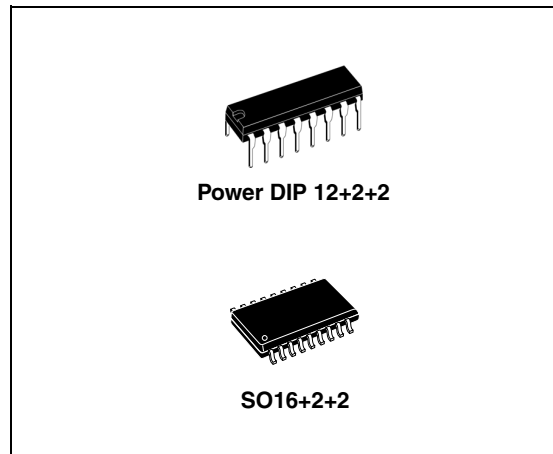
### Description

Each of the four switches is controlled by a logic input and all four are controlled by a common enable input. All inputs are TTL-compatible for direct connection to logic circuits.

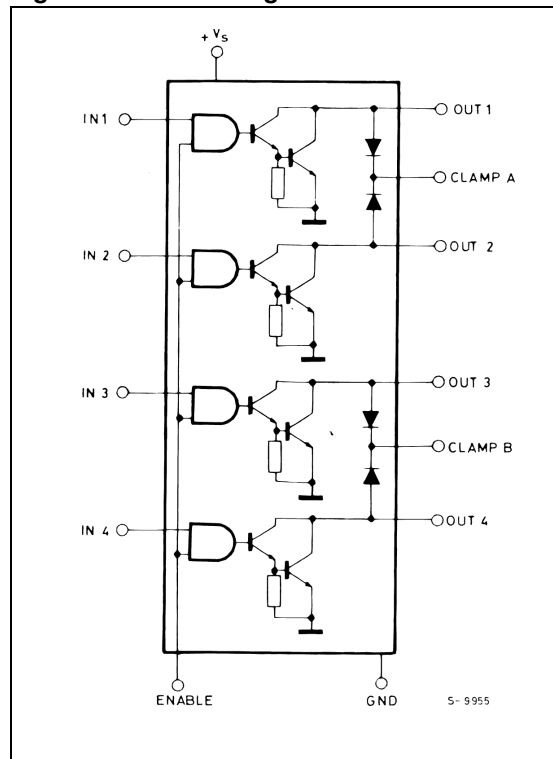
Each switch consists of an open-collector Darlington transistor plus a fast diode for switching applications with inductive device loads. The emitters of the four switches are commoned. Any number of inputs and outputs of the same device may be paralleled.

**Table 1. Device summary**

Order code	Package
E-L6221AS	Power DIP
E-L6221AD	SO16+2+2
E-L6221AD013TR	SO16+2+2 (tape and reel)
E-L6221C/CD/CN	Obsolete product



**Figure 1. Block diagram**



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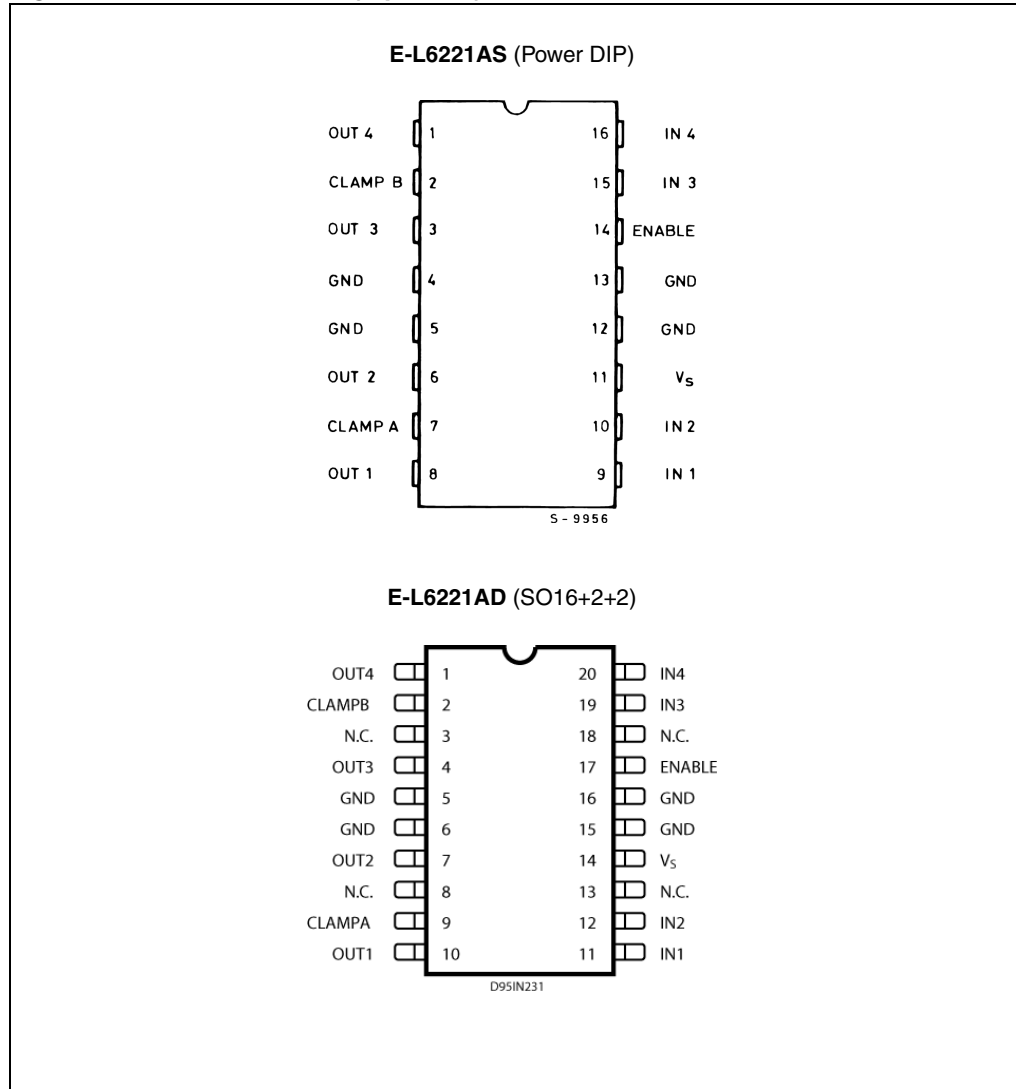
# 1 Thermal data

**Table 2. Thermal data**

Symbol	Parameter	SO20	Power DIP	Unit
$R_{th\ j-pins}$	Thermal resistance junction-pins max.	17	14	°C/W
$R_{th\ j-amb}$	Thermal resistance junction-ambient max.	80	80	°C/W

## 2 Pin information

Figure 2. Pin connections (top views)



**Table 3. Truth table<sup>(1)</sup>**

Enable	Input	Power out
H	H	ON
H	L	OFF
L	X	OFF

1. For each input: H = High level, L = Low level

**Table 4. Pin description<sup>(1)</sup>**

Name	Function
IN 1	Input to driver 1
IN 2	Input to driver 2
OUT 1	Output of driver 1
OUT 2	Output of driver 2
CLAMP A	Diode clamp to driver 1 and driver 2
IN 3	Input to driver 3
IN 4	Input to driver 4
OUT 3	Output of driver 3
OUT 4	Output of driver 4
CLAMP B	Diode clamp to driver 3 and driver 4
ENABLE	Enable input to all drivers
V <sub>S</sub>	Logic supply voltage
GND	Common ground

1. See [Figure 1: Block diagram](#)

### 3 Absolute maximum ratings

Table 5. Absolute maximum ratings

Symbol	Parameter	Value	Unit
$V_o$	Output voltage	50	V
$V_s$	Logic supply voltage	7	V
$V_{IN}, V_{EN}$	Input voltage, enable voltage	$V_s$	
$I_C$	Continuous collector current (for each channel)	1.8	A
$I_C$	Collector peak current (repetitive, duty cycle = 10% $t_{on} = 5$ ms)	2.5	A
$I_C$	Collector peak current (non repetitive, $t = 10$ $\mu$ s)	3.2	A
$T_{op}$	Operating temperature range (junction)	-40 to +150	$^{\circ}$ C
$T_{stg}$	Storage temperature range	-55 to +150	$^{\circ}$ C
$I_{sub}$	Output substrate current	350	mA
$P_{tot}$	Total power dissipation at:		
	$T_{pins} = 90$ $^{\circ}$ C (Power DIP)	4.3	W
	$T_{case} = 90$ $^{\circ}$ C (SO20)	3.5	W
	$T_{amb} = 70$ $^{\circ}$ C (Power DIP)	1	W
	$T_{amb} = 70$ $^{\circ}$ C (SO20)	1	W

## 4 Electrical characteristics

Note: Refer to the test circuits [Figure 3](#) to [Figure 10](#) ( $V_S = 5\text{ V}$ ,  $T_{amb} = 25\text{ °C}$  unless otherwise specified).

**Table 6. Electrical characteristics**

Symbol	Parameter	Test condition	Min.	Typ.	Max.	Unit
$V_S$	Logic supply voltage	-	4.5	-	5.5	V
$I_S$	Logic supply current	All outputs ON, $I_C = 0.7\text{ A}$	-	-	20	mA
		All outputs OFF	-	-	20	mA
$V_{CE(sus)}$	Output sustaining voltage	$V_{IN} = V_{INL}$ , $V_{EN} = V_{ENH}$ $I_C = 100\text{ mA}$	46	-	-	V
$I_{CEX}$	Output leakage current	$V_{CE} = 50\text{ V}$ $V_{IN} = V_{INL}$ , $V_{EN} = V_{ENH}$	-	-	1	mA
$V_{CE(sat)}$	Collector emitter saturation voltage (one input on, all others inputs off.)	$V_S = 4.5\text{ V}$	-	-	1	V
		$V_{IN} = V_{INH}$ , $V_{EN} = V_{ENH}$ $I_C = 0.6\text{ A}$	-	-	1.2	
		$I_C = 1\text{ A}$	-	-	1.6	
		$I_C = 1.8\text{ A}$	-	-	1.6	
$V_{INL}$ , $V_{ENL}$	Input low voltage	-	-	-	0.8	V
$I_{INL}$ , $I_{ENL}$	Input low current	$V_{IN} = V_{INL}$ , $V_{EN} = V_{ENL}$	-	-	-100	$\mu\text{A}$
$V_{INH}$ , $V_{ENH}$	Input high voltage	-	2.0	-	-	V
$I_{INH}$ , $I_{ENH}$	Input high current	$V_{IN} = V_{INH}$ , $V_{EN} = V_{ENH}$	-	-	10	$\mu\text{A}$
$I_R$	Clamp diode leakage current	$V_R = 50\text{ V}$ , $V_{EN} = V_{ENH}$ $V_{IN} = V_{INL}$	-	-	100	$\mu\text{A}$
$V_F$	Clamp diode forward voltage	$I_F = 1\text{ A}$	-	-	1.6	V
		$I_F = 1.8\text{ A}$	-	-	2.0	V
$t_{d(on)}$	Turn-on delay time	$V_p = 5\text{ V}$ , $R_L = 10\Omega$	-	-	2	$\mu\text{s}$
$t_{d(off)}$	Turn-off delay time	$V_p = 5\text{ V}$ , $R_L = 10\Omega$	-	-	5	$\mu\text{s}$
$\Delta I_S$	Logic supply current variation	$V_{IN} = 5\text{ V}$ , $V_{EN} = 5\text{ V}$ $I_{out} = -300\text{ mA}$ for each channel	-	-	120	mA

## 5 Test circuits

Note: Pin numbers without parentheses apply to the Power DIP package.  
Pin numbers in parentheses are not applicable.

Figure 3. Logic supply current

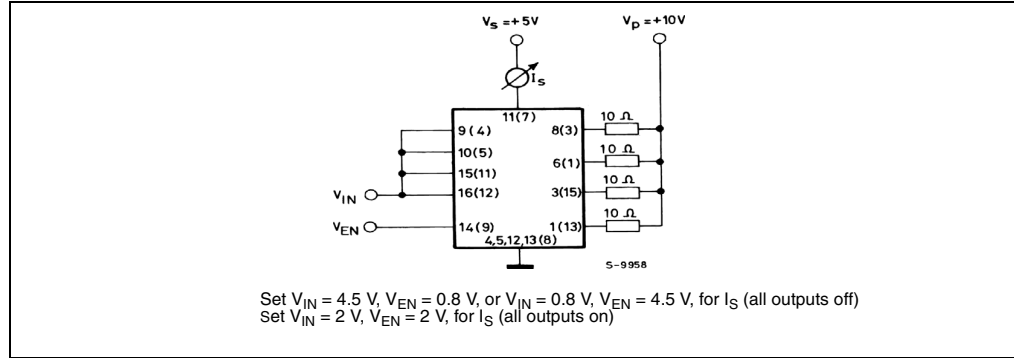


Figure 4. Output sustaining voltage

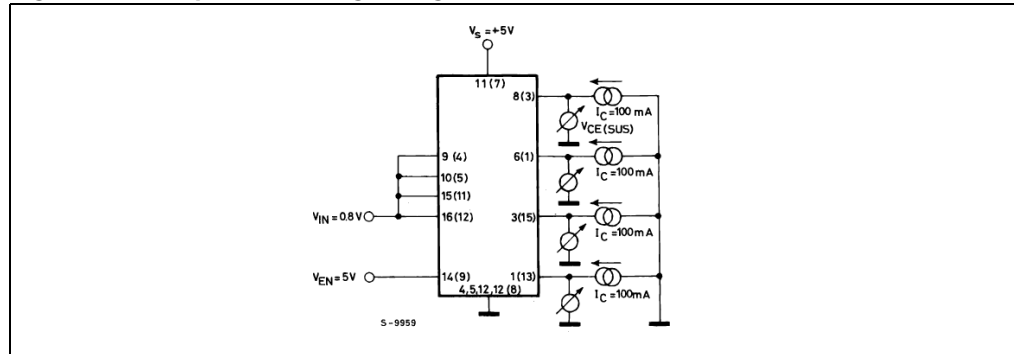
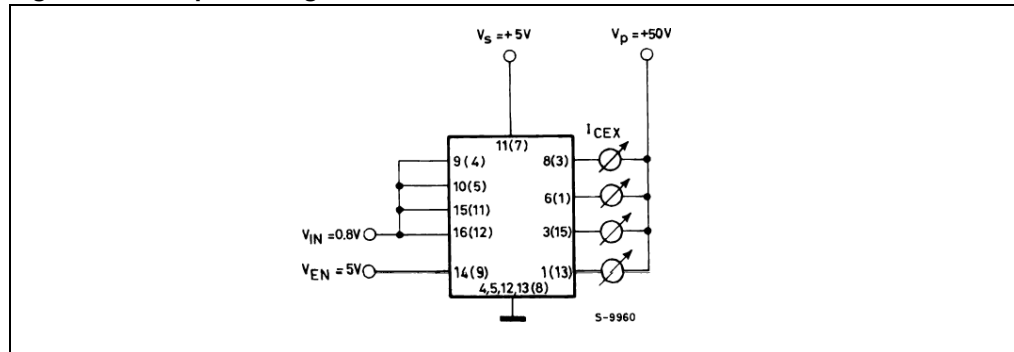
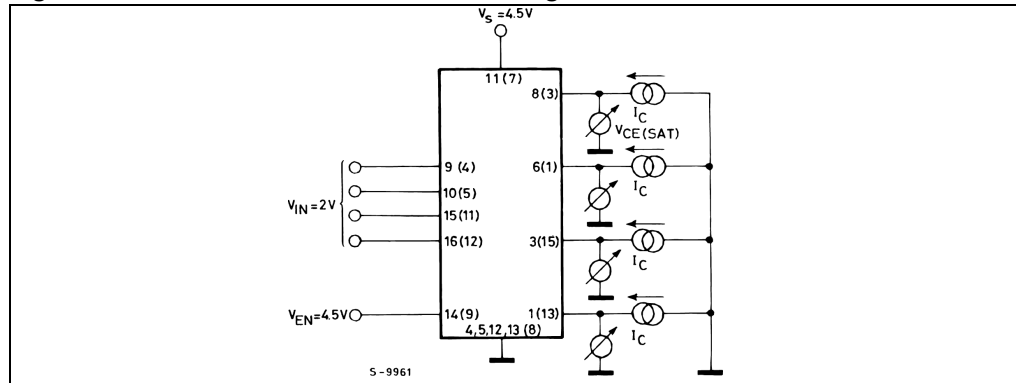


Figure 5. Output leakage current

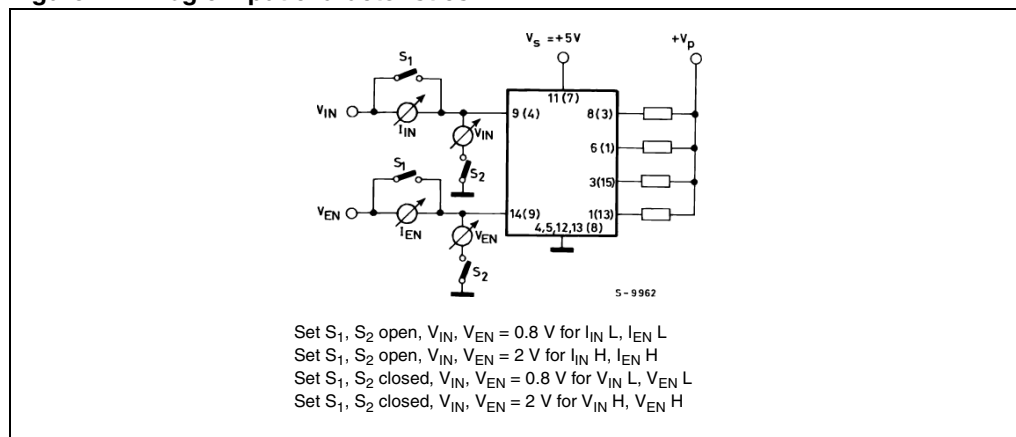




**Figure 6. Collector-emitter saturation voltage**



**Figure 7. Logic input characteristics**



**Figure 8. Clamp-diode leakage current**

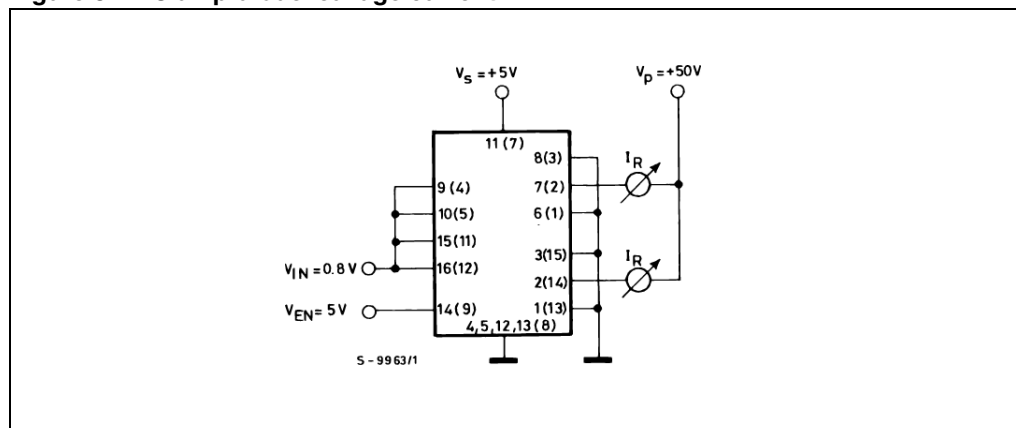


Figure 9. Clamp-diode forward voltage

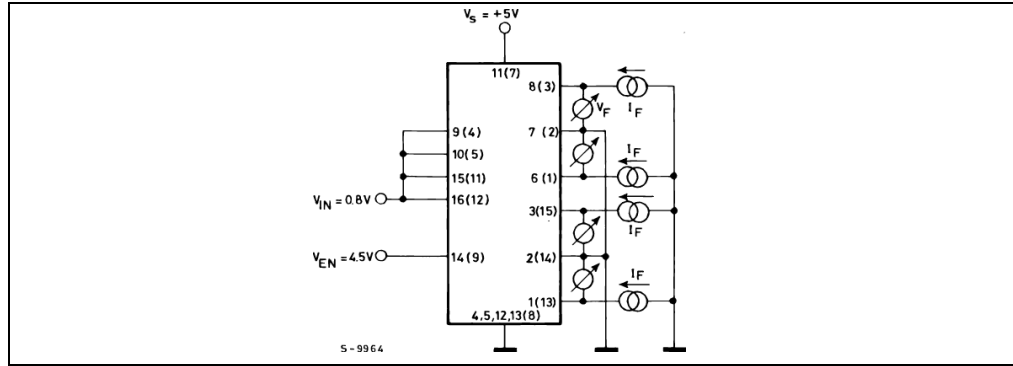


Figure 10. Switching time test circuit

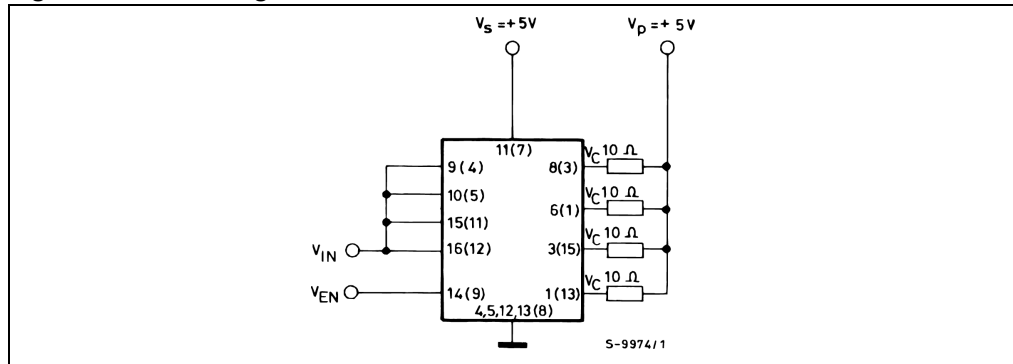
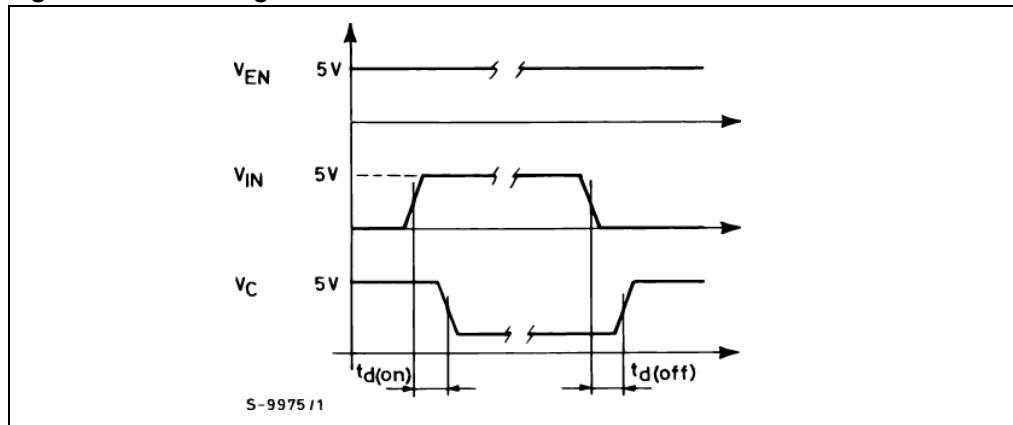
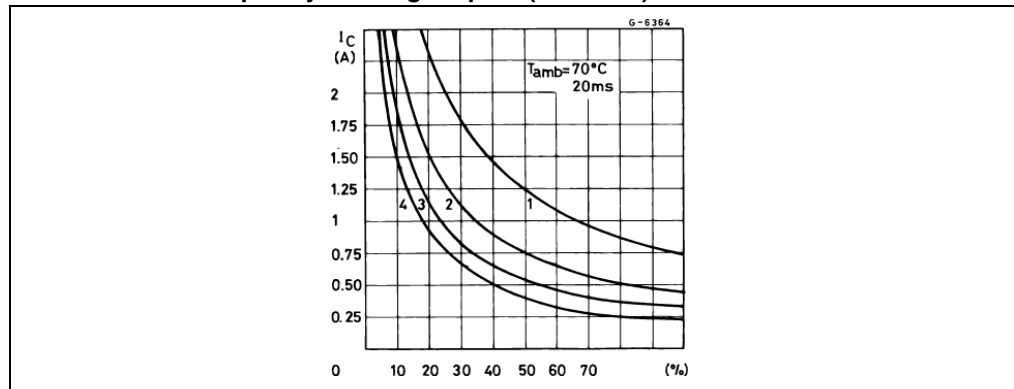


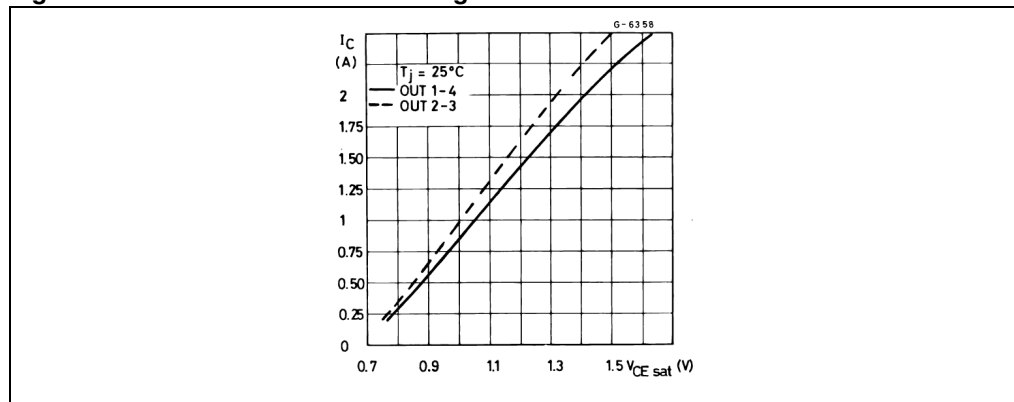
Figure 11. Switching time waveforms



**Figure 12. Allowed peak collector current versus duty cycle for 1, 2, 3 or 4 contemporary working outputs (L6221AS)**



**Figure 13. Collector saturation voltage versus collector current**



**Figure 14. Free-wheeling diode forward voltage versus diode current**

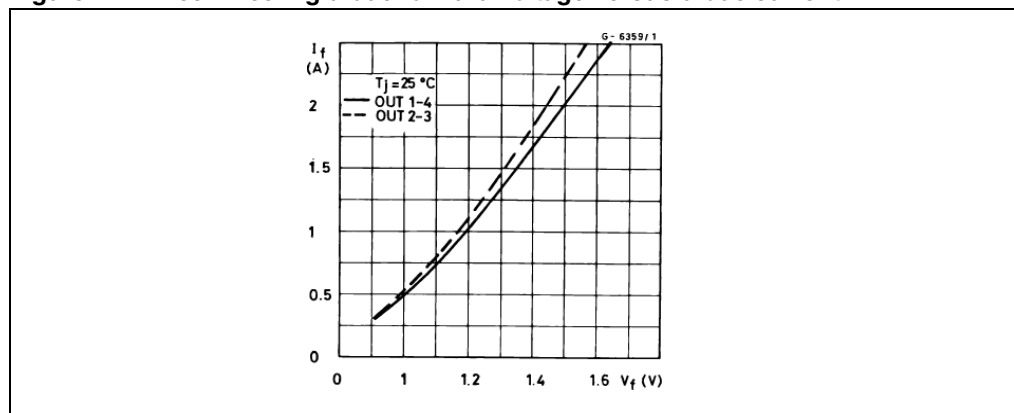


Figure 15. Collector saturation voltage versus junction temperature at  $I_C = 1\text{ A}$

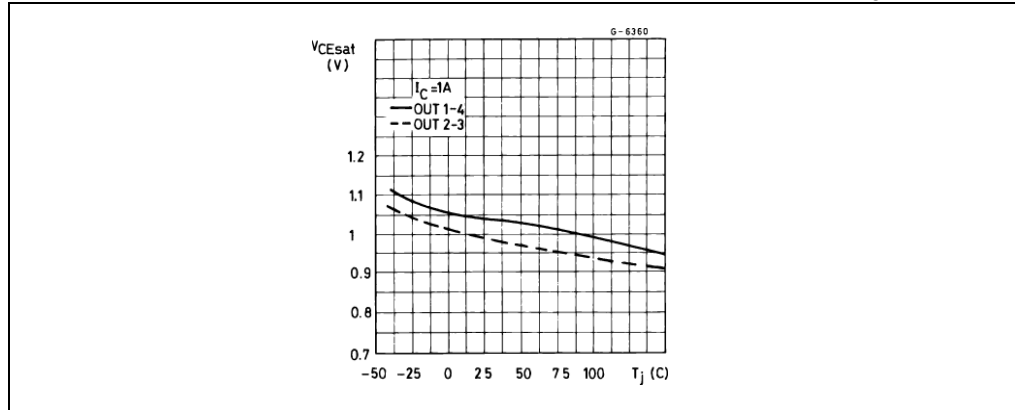


Figure 16. Free-wheeling diode forward voltage versus junction temperature at  $I_F = 1\text{ A}$

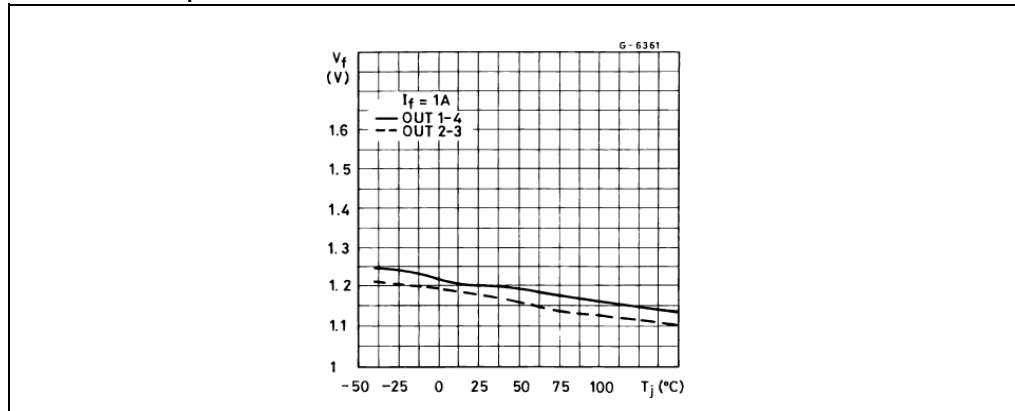


Figure 17. Saturation voltage against junction temperature

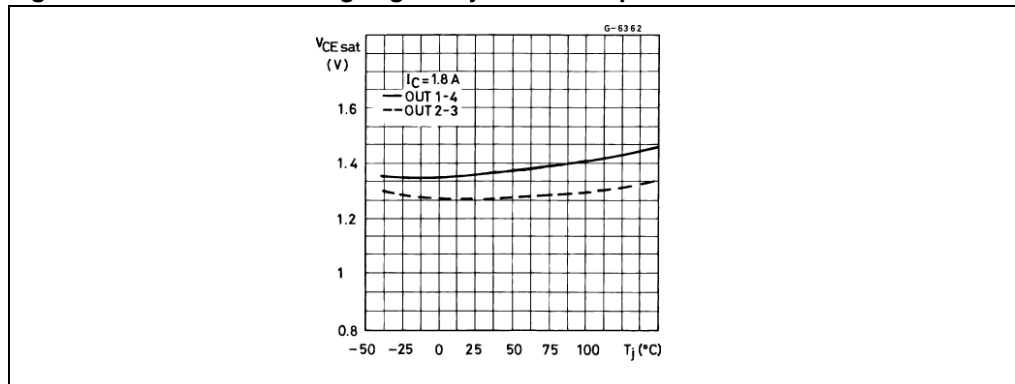
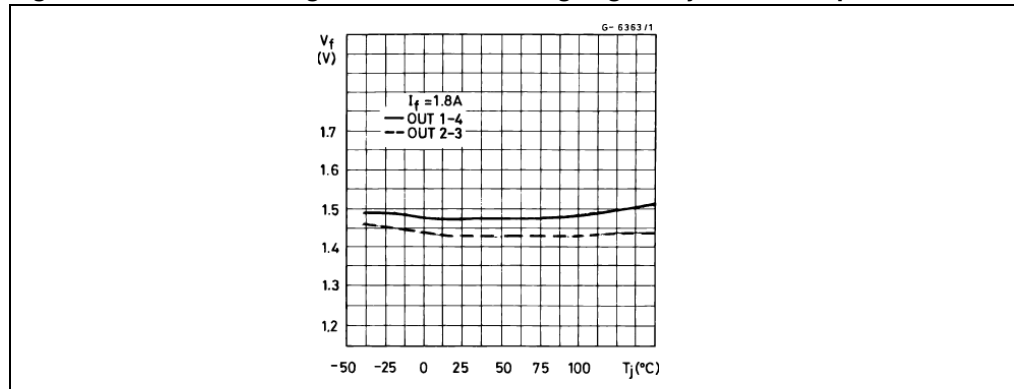


Figure 18. Free-wheeling diode forward voltage against junction temperature



## 6 Application information

When inductive loads are driven by the L6221, a Zener diode in series with the integral free-wheeling diodes increases the voltage across which energy stored in the load is discharged and therefore speeds the current decay (*Figure 19*).

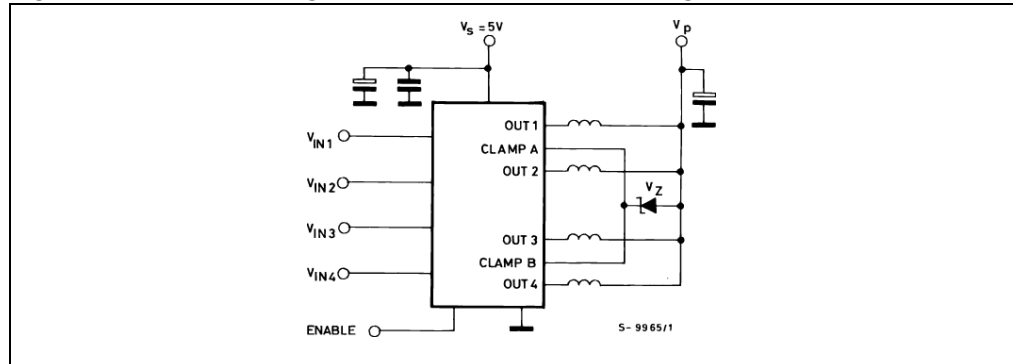
For reliability it is suggested that the Zener is chosen so that

$$V_p + V_z < 35 \text{ V}$$

There are two reasons for this:

- The Zener voltage changes in temperature and current.
- The instantaneous power must be limited to avoid the reverse second breakdown.

**Figure 19. Free-wheeling diode connection when driving inductive loads**



Care must be taken to ensure that the collectors are placed close together to avoid different current partitioning at turn-off.

It is suggested to put in parallel channel 1 and 4 and channel 2 and 3 as shown in *Figure 20* for the similar electrical characteristics of the logic section (turn-on and turn-off delay time) and the power stages (collector saturation voltage, free-wheeling diode forward voltage).

Figure 20. Driver for solenoids up to 3 A

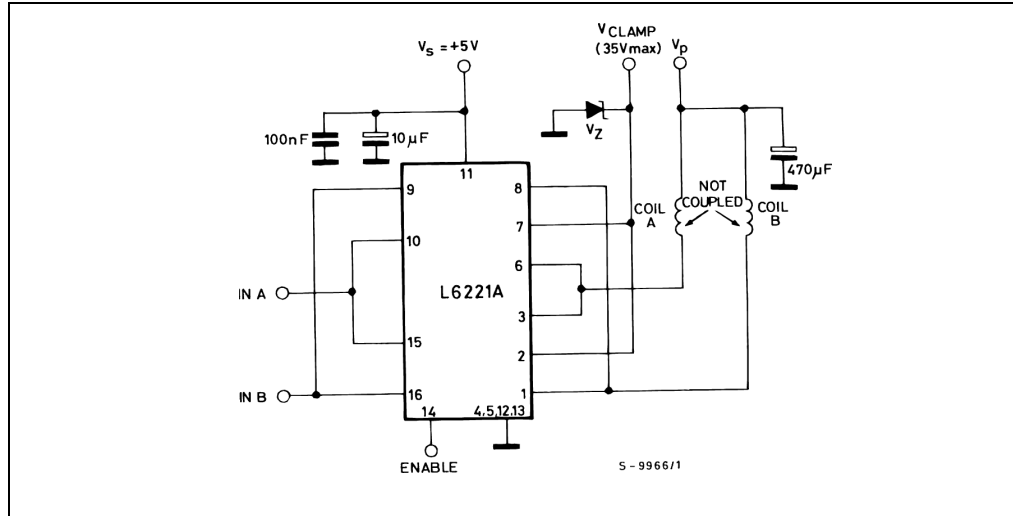


Figure 21. Saturation voltage versus collector current

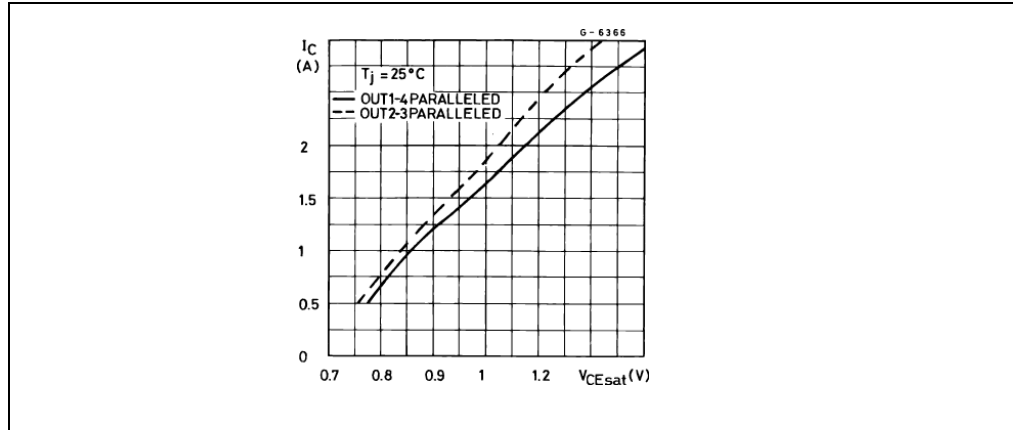
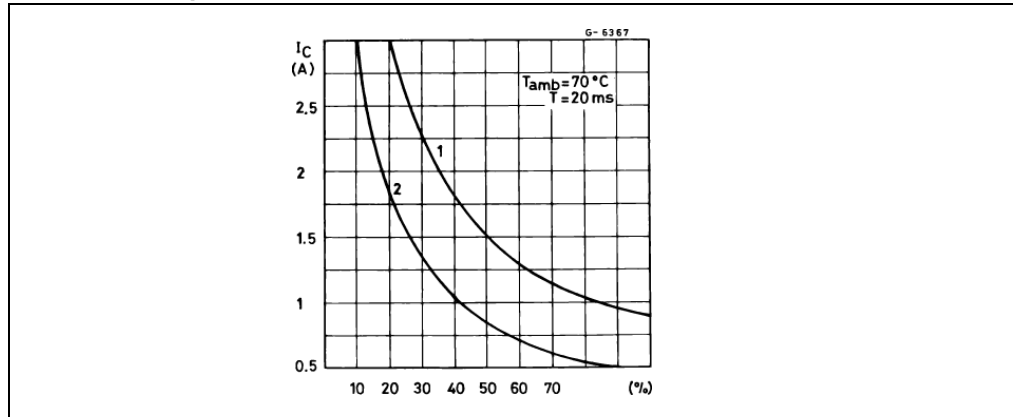


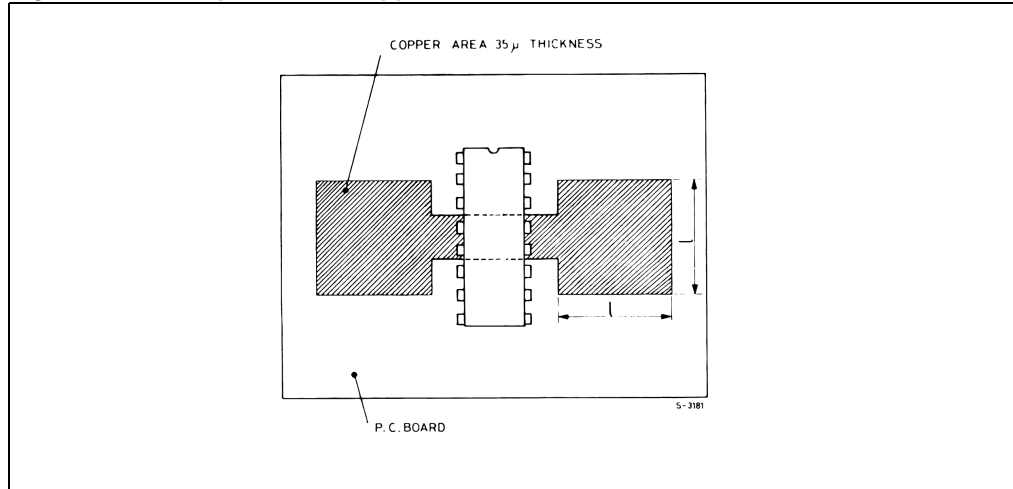
Figure 22. L6221AS peak collector current versus duty cycle for 1 or 2 paralleled outputs driven



## 7 Mounting instructions

The  $R_{th\ j-amb}$  of the E-L6221AS can be reduced by soldering the GND pins to a suitable copper area of the printed circuit board (*Figure 23*) or to an external heat sink (*Figure 24*).

**Figure 23. Example of PCB copper area used as heat sink**



**Figure 24. External heat sink mounting example**

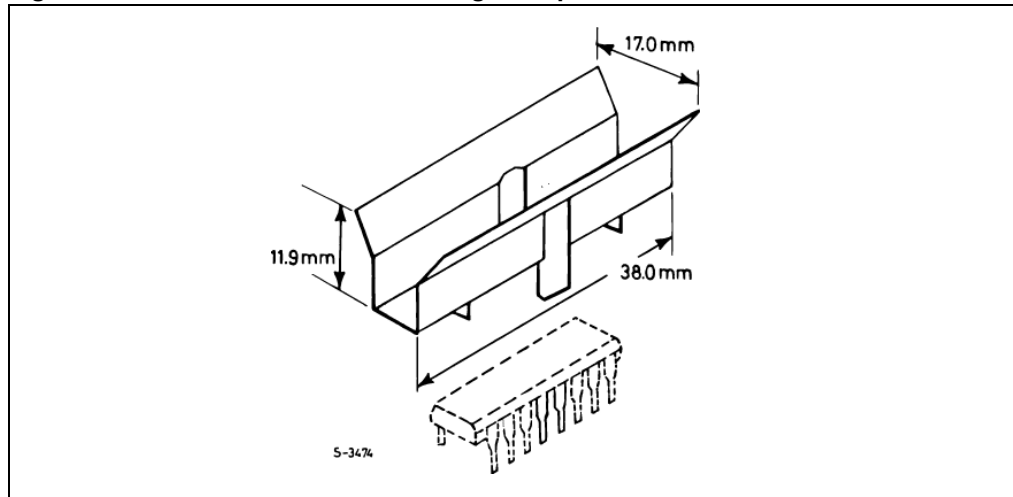
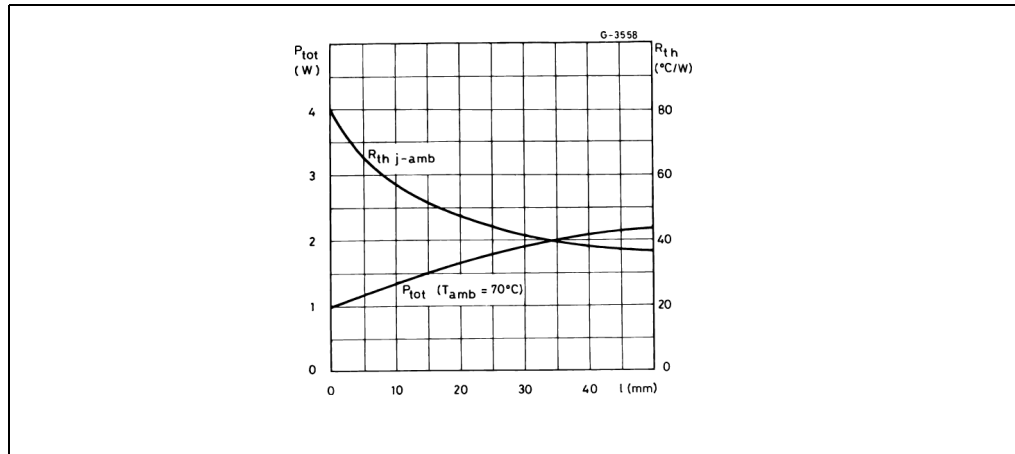




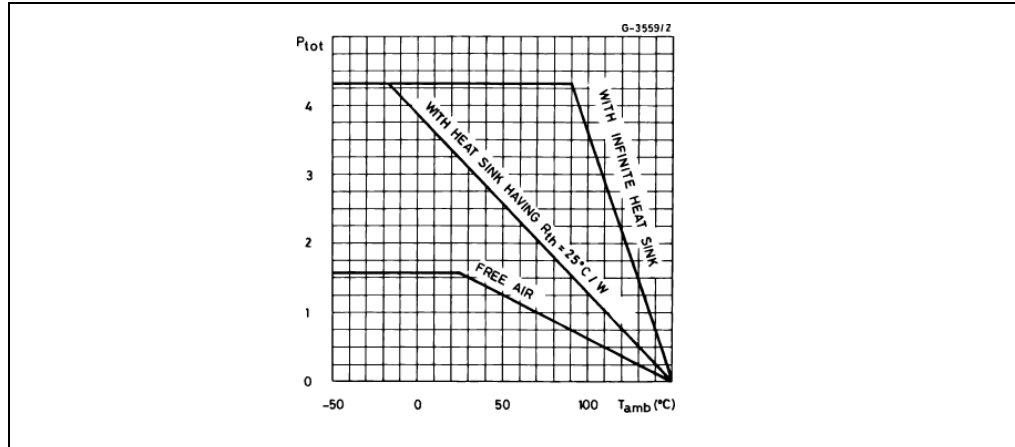
Figure 25 shows the maximum dissipable power  $P_{tot}$  and the  $R_{th\ j-amb}$  as a function of the side " $\alpha$ " of two equal square copper areas having a thickness of  $35\ \mu\text{m}$  (1.4 mils). During soldering the pins temperature must not exceed  $260\ ^\circ\text{C}$  and the soldering time must not be longer than 12 seconds.

The external heat sink or printed circuit copper area must be connected to electrical ground.

**Figure 25. Maximum dissipable power and junction-to-ambient thermal resistance versus side " $\alpha$ "**



**Figure 26. Maximum allowable power dissipation versus ambient temperature**

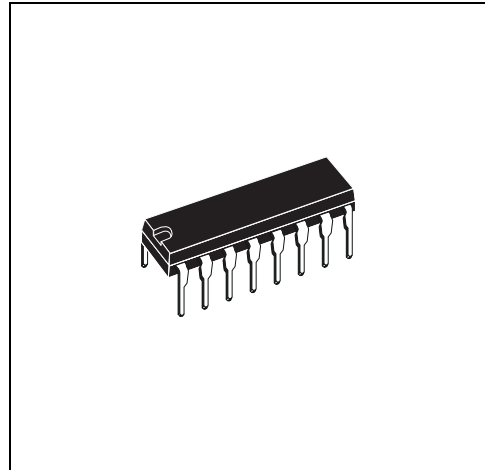


## 8 Package mechanical data

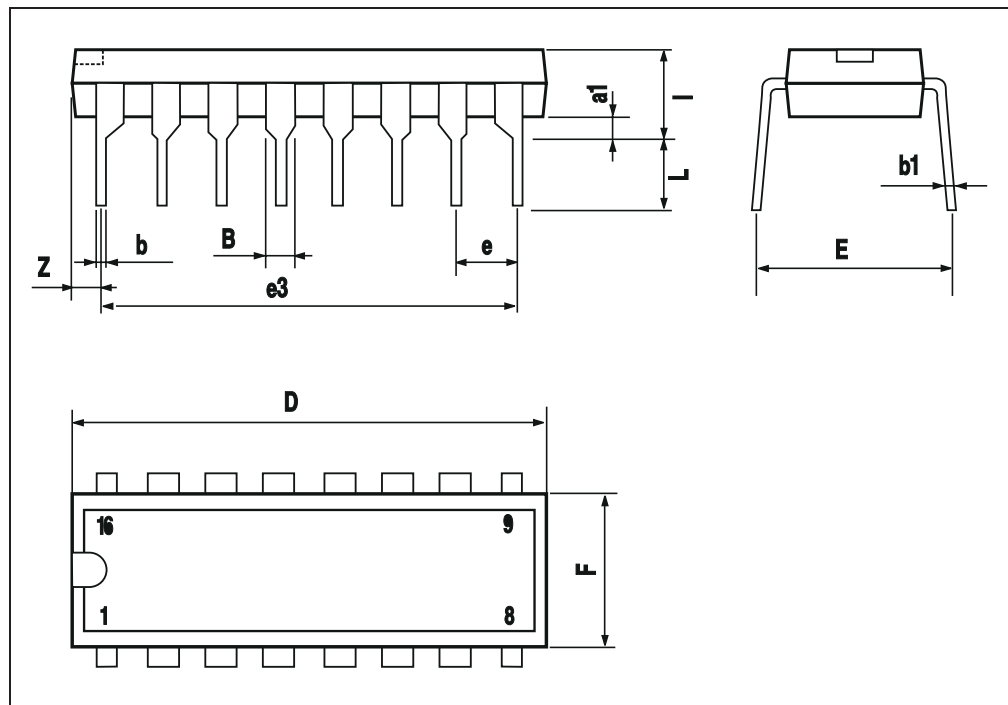
In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: [www.st.com](http://www.st.com). ECOPACK® is an ST trademark.

DIM.	mm			inch		
	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
a1	0.51			0.020		
B	0.85		1.40	0.033		0.055
b		0.50			0.020	
b1	0.38		0.50	0.015		0.020
D			20.0			0.787
E		8.80			0.346	
e		2.54			0.100	
e3		17.78			0.700	
F			7.10			0.280
l			5.10			0.201
L		3.30			0.130	
Z			1.27			0.050

**OUTLINE AND MECHANICAL DATA**



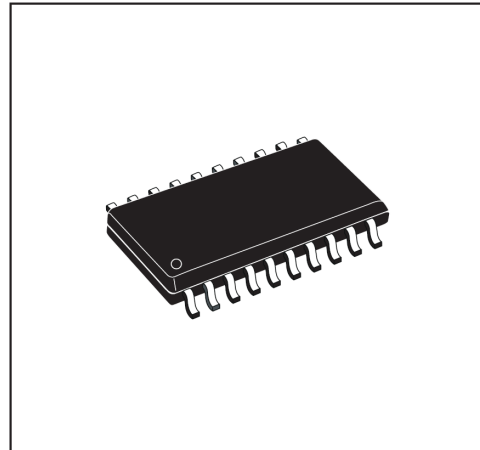
**Power DIP 16**



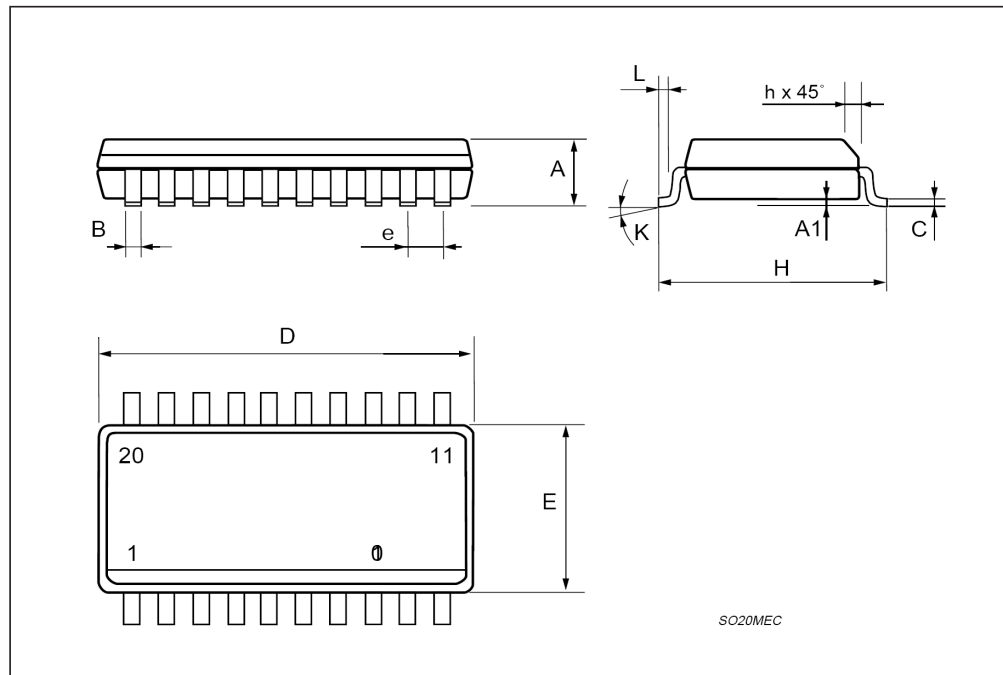
**Package mechanical data**

DIM.	mm			inch		
	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
A	2.35		2.65	0.093		0.104
A1	0.1		0.3	0.004		0.012
B	0.33		0.51	0.013		0.020
C	0.23		0.32	0.009		0.013
D	12.6		13	0.496		0.512
E	7.4		7.6	0.291		0.299
e		1.27			0.050	
H	10		10.65	0.394		0.419
h	0.25		0.75	0.010		0.030
L	0.4		1.27	0.016		0.050
K	0° (min.)8° (max.)					

**OUTLINE AND MECHANICAL DATA**



**SO20**



## 9 Revision history

Table 7. Document revision history

Date	Revision	Changes
14-Jan-2004	2	Released in EDOCS
19-Jan-2009	3	Document reformatted. Inserted title for <a href="#">Figure 19</a> . Removed reference to obsolete product L6221N and the associated package (multiwatt-15).
30-Mars-2009	4	Obsolete products E-L6221C/CD/CN added in <a href="#">Table 1</a> .

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